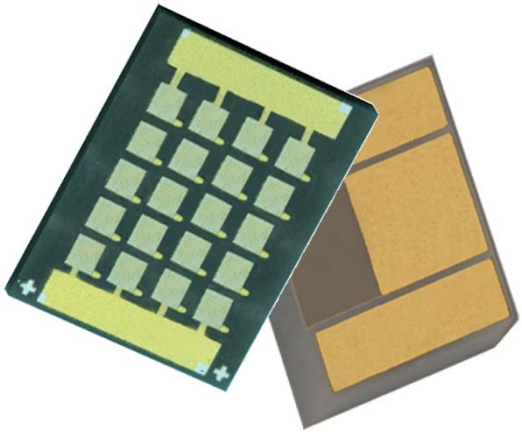
REMTEC®

CERAMIC PACKAGING SOLUTIONS FOR OPTIMUM PERFORMANCE

FOR IMMEDIATE RELEASE

Remtec Expands its Submount Offerings for Packaging of Laser Diodes, LEDs and Photo Diodes

Norwood, MA. December 15, 2011. Remtec, Inc., a leading supplier of ceramic packaging solutions with Plated Copper on Thick Film (PCTF) technology, has added new capabilities for Laser Diode, LED and Photo Diode submounts and substrates. Now designers have a wider variety of packaging options with ceramic submounts (alumina, beryllia, and aluminum nitride), metal heat sinks and enhanced plated gold tin metallization. These new improvements, along with the diverse advantages of PCTF technology, permit designers to use many more options to gain higher performance from smaller, more cost-effective packages for electro-optical applications.



Remtec's laser and photo diode submounts offer 25-75 micron thick copper metallization with unique Zero Pullback Metallization from a burr-free ceramic edge. This greatly enhances performance of edge-emitting diodes. An important additional benefit is low cost, selective Gold Tin plating on submounts, used for both edge-emitting and VEXEL laser diodes. In addition to ceramic submounts, the Gold Tin option can also be applied to Copper Tungsten submounts and laser bars. These features provide the designer with more cost-effective and simplified packaging solutions than previously available for laser and photo diode submounts.

Many of the time-proven advantages of PCTF technology and the new packaging developments for laser and photo diodes are equally applicable to LED substrates. Designers of LED packaging may select alumina, beryllium oxide and aluminum nitride ceramic substrates with 25-75 micron thick metallization and plugged vias, wraparounds as well as multi-layer configurations. A wide variety of plating finishes including selective Gold, Palladium and Gold Tin allows the use of various soldering materials and assembly techniques: gold wire bonding, brazing and epoxy die attach. These versatile packaging options allow designers of LED devices to improve performance and to bring their products into production faster and with lower engineering costs.

Applications using laser and photo diode submounts and LED substrates include laser welding, cutting and marking systems; medical applications such as blood-oxygen sensors, trans-dermal delivery systems for medications and laser imaging; cosmetic applications for skin rejuvenation and hair removal; UV curing of light-sensitive dental materials; UV curing of industrial inks and adhesives; 3D digital printing; cinematic lighting and many other products.

Remtec, a RoHS compliant ISO 9001:2008 certified company, operates a manufacturing facility totaling 35,000 sq. ft. in Norwood, MA. Remtec provides custom and semi-custom packaging solutions using its versatile PCTF copper metallization technology for DC power electronics, optoelectronics and MW/RF products in military, industrial and commercial industries.

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